

# MECHANICAL CASE OUTLINE

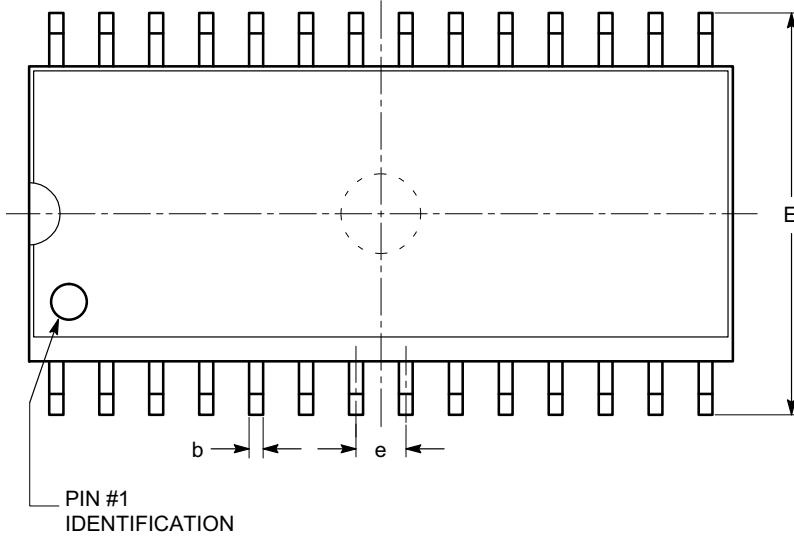
## PACKAGE DIMENSIONS

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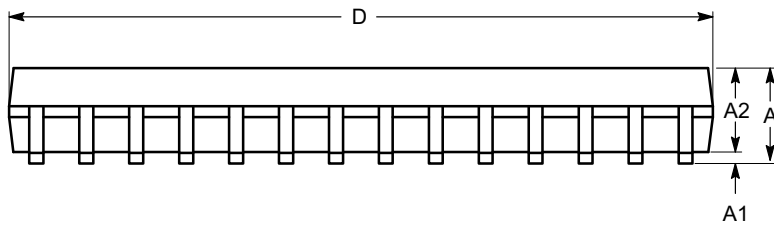
SOIC-28, 300 mils  
CASE 751BM-01  
ISSUE O

DATE 19 DEC 2008

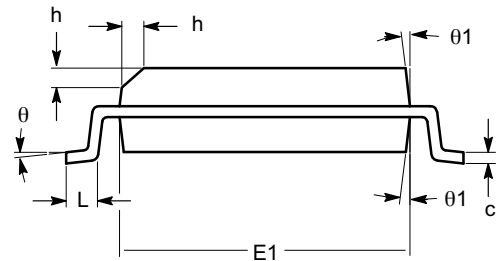


TOP VIEW

SYMBOL	MIN	NOM	MAX
A	2.35		2.65
A1	0.10		0.30
A2	2.05		2.55
b	0.31		0.51
c	0.20		0.33
D	17.78		18.03
E	10.11		10.51
E1	7.34		7.60
e	1.27 BSC		
h	0.25		0.75
L	0.40		1.27
$\theta$	0°		8°
$\theta_1$	5°		15°



SIDE VIEW



END VIEW

**Notes:**

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MS-013.

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<b>DESCRIPTION:</b>	<b>SOIC-28, 300 MILS</b>	<b>PAGE 1 OF 1</b>

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